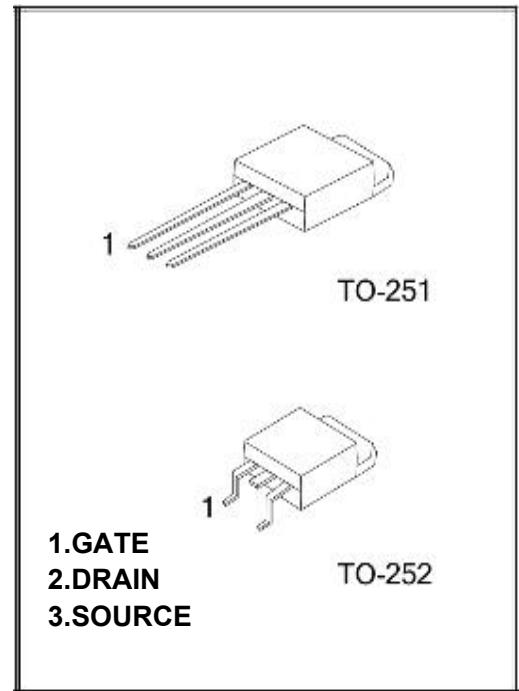




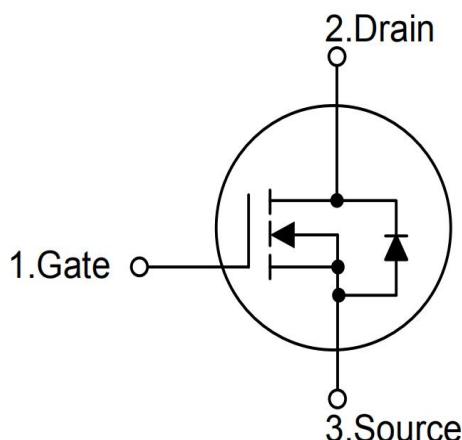
SHENZHEN MENGKE ELECTRONICS TECHNOLOGY CO.,LTD

TO-252-2L Plastic-Encapsulate MOSFETS**MK2N60****N-Channel 600-V(D-S) Power MOSFET**

V(BR)DSS	RDS(on)MAX	ID
600V	4.5Ω@ 10V	2A

**General Description:**

The MK 2N60 is a high voltage MOSFET and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristics. This power MOSFET is usually used at high speed switching applications in power supplies, PWM motor controls, high efficient DC to DC converters and bridge circuits.

**Equivalent Circuit :****FEATURE:**

- Fast switching capability
- Avalanche energy specified
- Improved dv/dt capability, high ruggedness
- Low reverse transfer capacitance

**Maximum ratings ( Ta=25°C unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	VDS	600	V
Gate-Source Voltage	VGS	±30	
Continuous Drain Current	ID	2	A
Pulsed Diode Current	IDM	8	
Power Dissipation	PD	44	W
Thermal Resistance from Junction to Ambient (t≤10s)	R <sub>θJA</sub>	100	°C/W
Operating Junction	T <sub>J</sub>	150	°C
Storage Temperature	T <sub>STG</sub>	-55~+150	



## MOSFET ELECTRICAL CHARACTERISTICS

## Static Electrical Characteristics (Ta = 25 °C Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static</b>						
Drain-source breakdown voltage	V(BR)DSS	VGS = 0V, ID = 250µA	600			V
Gate-source threshold voltage	VGS(th)	VDS = VGS, ID = 250µA	1.5		4	V
Gate-source leakage	IGSS	VDS = 0V, VGS = ±30V			±100	nA
Zero gate voltage drain current	IDSS	VDS = 600V, VGS = 0V			10	µA
Drain-source on-state resistancea	RDS(on)	VGS = 10V, ID = 1A		3.6	4.5	Ω
Forward transconductancea	gfs	VDS = 300V, ID = 1A		25		S
Diode forward voltage	VSD	IS=1A, VGS=0V		0.8	1.5	V
<b>Dynamic</b>						
Input capacitance	Ciss	VDS = 25V, VGS = 0V, f=1MHz		270	350	pF
Output capacitance	Coss			40	50	pF
Reverse transfer capacitanceb	Crss			5	7	pF
Total gate charge	Qg	VDS = 300V, VGS = 10V, ID = 2A		9.0	11	nC
Gate-source charge	Qgs			1.6		nC
Gate-drain charge	Qgd			4.3		nC
Gate resistance	Rg	f=1MHz		10		Ω
<b>Switchingb</b>						
Turn-on delay time	td(on)	VDD= 300V RL= 50Ω, ID ≈ 2A, VGEN= 10V, Rg= 50Ω		10	30	ns
Rise time	tr			25	60	ns
Turn-off delay time	td(off)			20	50	ns
Fall time	tf			25	60	ns
<b>Drain-Source Diode Characteristics</b>						
Body Diode Reverse Recovery Time	trr	If= 2A, dl/dt=100A/us		180		ns
Body Diode Reverse Recovery Charge	grr	If= 2A, dl/dt=100A/us		0.72		UC
Continuous Source-Drain Diode Current	IS				2	A
Pulsed Diode forward Current	ISM				8	A

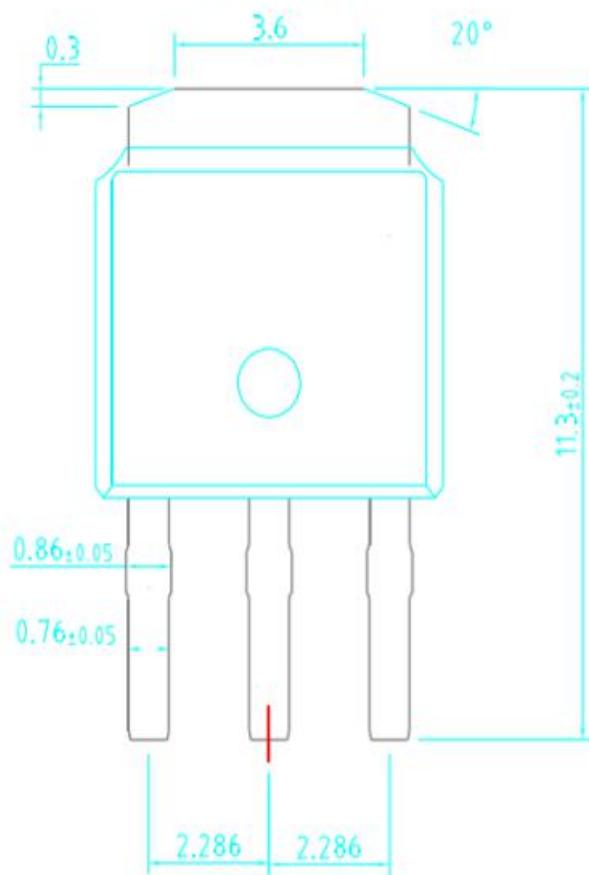
**Note :**

1. Repetitive Rating : Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t < 10 sec.
3. Pulse Test : Pulse Width≤300µs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production testing.



PACKAGE OUTLINE DIMENSIONS :

TO-251



TO-252

